

P-Ch MOSFET

General Description

The WSR88P06 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.

Features

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

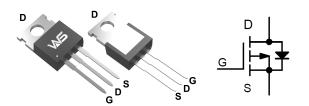
Product Summery

BVDSS	RDSON	ID
-60V	9.0mΩ	-88A

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

TO-220 Pin Configuration



Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	-60	V	
VGS	Gate-Source Voltage	±20	V	
ID@TC=25°C	Continuous Drain Current, -VGS @ -10V1	-88	Α	
ID@TC=100°C	Continuous Drain Current, -VGS @ -10V1	-50	Α	
IDM	Pulsed Drain Current2	-320	Α	
EAS	Single Pulse Avalanche Energy3	450	mJ	
IAS	Avalanche Current	41	Α	
PD@TC=25°C	Total Power Dissipation4	110	W	
TSTG	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	

Thermal Data

Symbol	Parameter	Rating	Units
RθJA	Thermal Resistance Junction-Ambient 1	1.1	°C/W
RθJC	Thermal Resistance Junction-Case1	60	°C/W



Electrical Characteristics (Tc=25 ℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	Vgs=0V , In=-250uA	-60	-68		V
△BVDSS/△TJ	BVpss Temperature Coefficient	Reference to 25℃ , I _D =-1mA		-0.035		V/°C
Rds(on)	Static Drain-Source On-Resistance2	V _G S=-10V , I _D =-20A		9.0	11	mΩ
		Vgs=-4.5V , Ip=-15A		12	16	
VGS(th)	Gate Threshold Voltage	V V I 050	-1.0	-1.8	-2.5	V
$\triangle V$ GS(th)	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =-250uA		4.28		mV/℃
lace	Drain-Source Leakage Current	V _{DS} =-60V , V _{GS} =0V , T _J =25℃			1	- uA
IDSS		V _{DS} =-60V , V _{GS} =0V , T _J =55℃			5	
Igss	Gate-Source Leakage Current	Vgs=±20V , Vps=0V			±100	nA
gfs	Forward Transconductance	Vps=-5V , Ip=-20A		50		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.0		Ω
Qg	Total Gate Charge (-4.5V)	Vps=-30V , Vgs=-10V , lp=- 20A		56		nC
Qgs	Gate-Source Charge			11		
Qgd	Gate-Drain Charge			9		
Td(on)	Turn-On Delay Time	V _{DD} =-30V , V _{GS} =-10V , R _G =3 Ω, I _D =-20A		4.5		- ns
Tr	Rise Time			2.5		
Td(off)	Turn-Off Delay Time			14.5		
Tf	Fall Time			3.8		
Ciss	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		3500		pF
Coss	Output Capacitance			600		
Crss	Reverse Transfer Capacitance			25		
ls	Continuous Source Current _{1,5}	VV0V - Ferry Over-1			-80	Α
lsм	Pulsed Source Current _{2,5}	V _G =V _D =0V , Force Current			-240	Α
VsD	Diode Forward Voltage2	Vgs=0V , Is=-1A , TJ=25℃			-1.2	V

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- $2\sqrt{100}$ The data tested by pulsed , pulse width ≤ 300 us , duty cycle $\leq 2\%$
- $3\sqrt{100}$ The EAS data shows Max. rating . The test condition is VDD =-48V,VGS =-10V,L=0.1mH,IAS =-41A
- 4√ The power dissipation is limited by 150°C junction temperature
- 5 The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.



Typical Characteristics

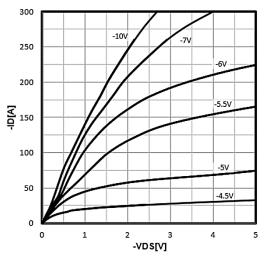


Figure 1. Type. Output Characteristics (Tj=25 ℃)

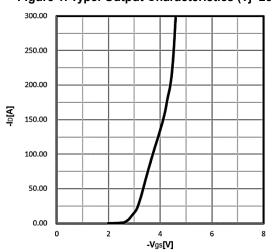


Figure 3. Type. transfer characteristics

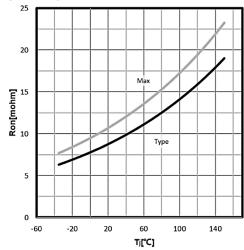


Figure 5. Drain-source on-state resistance RDS(on) =f(Tj); ID =80A; VGS =10V

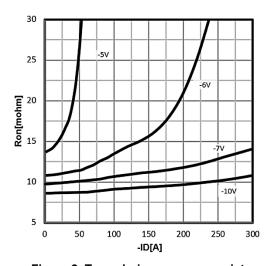


Figure 2. Type. drain-source on resistance

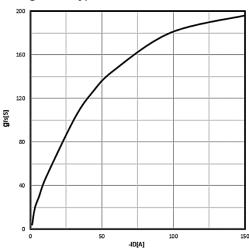


Figure 4. Type. forward transconductance

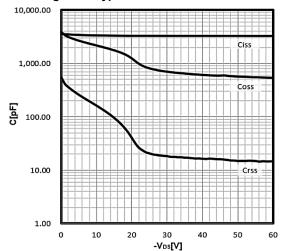


Figure 6 . Body-Diode Characteristics C=f(VDS); VGS =0V; f=1MHz

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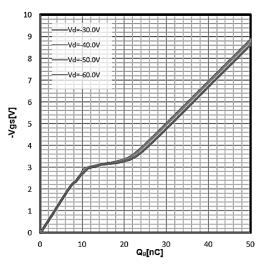


Figure 7. Typ. gate charge VGS =f(Q gate); ID =20A

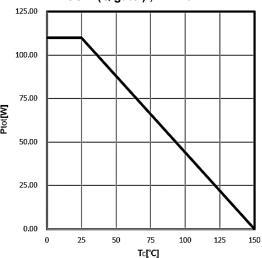


Figure 7. Power Dissipation

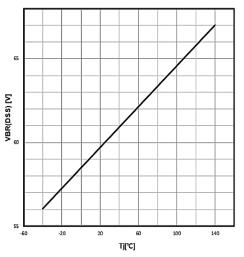


Figure 8. Drain Current Derating VBR(DSS) =f(T j); I D =250uA

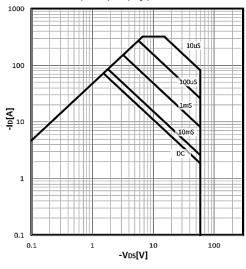


Figure 8. Safe operating area

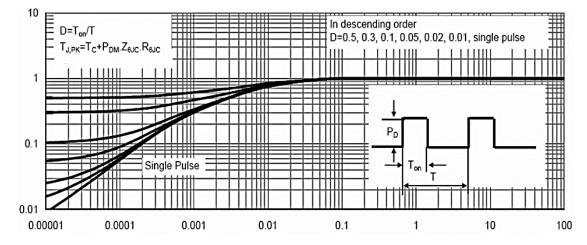


Figure 10. Max. transient thermal impedance

ZthJC =f(tp)



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